

Press Release

## Heraeus Electronics Brings Fully Matched Power Module Systems and DTS® Innovation to APEC 2026

Hanau, February 2026 – Heraeus Electronics will exhibit in Booth 1438 at APEC 2026 (IEEE Applied Power Electronics Conference and Exposition) at the Henry B. Gonzalez Convention Center in San Antonio, Texas. The company will showcase its power module portfolio of matched materials, highlighting how coordinated material choices across die attach, interconnection, and substrates can improve performance, reliability, and manufacturability.

At the center of the exhibit will be the Heraeus Electronics Die Top System (DTS®), including DTS® Gold and DTS® Silver. DTS® replaces conventional solder die attach and aluminum wire bonding with a fully sintered interconnection approach, delivering more than 50% higher die current capability and up to 50 times longer lifetime, while enabling junction temperatures above 200°C. These gains allow designers to reduce power derating and optimize module layouts without adding process complexity.

DTS® Gold is designed for applications requiring the highest electrical and mechanical performance, while DTS® Silver provides a cost-efficient alternative with a strong cost-per-ampere advantage. Both variants support one-step sintering of chip front and backside, use standard sintering and die-bonding equipment, and can be adapted to common chip designs.



In addition to DTS®, Heraeus Electronics will present complementary materials engineered to work together as part of an integrated power module system:

- **PowerCu Soft wires and ribbons** – Soft copper interconnect materials matched to DTS® properties, providing a wide bonding window and reliable electrical and thermal performance.
- **mAgic® PE338 die-attach** – A pressure sinter paste optimized for high-reliability die attach and offering stable thermal paths
- **mAgic® PE360 sintering materials** – Large-area silver sintering solutions for module attach that deliver uniform bond lines and strong thermal and mechanical stability at relatively low pressure and temperature.
- **Microbond® solder preforms** – Innolot®-based preforms designed for module-to-heatsink attachment, offering a balance of durability, processing simplicity, and material cost control.
- **Condura®.ultra metal-ceramic substrates** – Advanced silver-free AMB substrates combining high thermal conductivity with mechanical stability, supporting demanding power density and reliability requirements.



Heraeus Electronics will also highlight its engineering and application services, available through its global Technology and Application Centers. These services support customers with prototype builds, material matching, and reliability testing to help accelerate development, validate designs, and transition concepts into production.

Visitors to Booth 1438 can learn how Heraeus Electronics' matched material systems enable more predictable performance, faster development cycles, and scalable manufacturing for next-generation power electronics.

For more information about Heraeus Electronics and its power module solutions, visit [www.heraeus-electronics.com](http://www.heraeus-electronics.com).

### **About Heraeus**

Heraeus is a globally active, family-owned technology group. Based in Hanau, Germany, the company comprises 15 operating companies whose products and services span the Business Areas of Metals & Recycling, Healthcare, Semiconductor & Electronics, and Industrials. In fiscal year 2024, Heraeus generated revenues of €29.4 billion and employed roughly 15,200 people across 40 countries. This makes Heraeus one of the top ten largest family-owned enterprises in Germany.

**MATERIALS. INNOVATIONS. FOR GENERATIONS.**

### **About Heraeus Electronics**

Heraeus Electronics is a materials innovation partner for the electronics industry with global reach and local presence. The company develops material solutions for the automotive, power electronics and advanced semiconductor packaging market and offers its customers a broad product portfolio – from materials and material systems to services.

### **For more information, contact:**

Heraeus Electronics

Anja Ziegler

Head of Marketing Communication

[Anja.Ziegler@heraeus.com](mailto:Anja.Ziegler@heraeus.com)